

Hybrid-Filled Epoxy Molding Compositions

Disclosure Number

201202955

Technology Summary

Hybrid-filled epoxy molding compounds (EMCs) are a class of material that has the unique combination of characteristics of being low cost, electrically insulating, non-susceptible to magnetic fields, and having a thermally conductivity of at least 5 W/mK. This combination makes hybrid-filled EMCs attractive for use in power electronic and electric motor applications because their high thermal conductivity enables improved and new paradigms of thermal management on those applications. Their use will further enable the promotion of lower temperature of operation of electronic devices and electric motors thusly improving their reliability and increasing their lifetime.

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